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OIF members to demonstrate physical and link layer interoperability at SuperComm 2003

22 May 2003 Fremont, CA Lightwave -- The Optical Internetworking Forum (OIF) companies will demonstrate interoperability of the Forum's Physical and Link Layer (SUPERCOMM 2003 in Atlanta, June 3-5, Booth #10205. As a part of SUPERCOMM the OIF will also introduce its newest project, the Common Electrical I/O (CEI).

"The OIF's PLL Working Group is producing some incredibly original technical work Ciena Corp., president of the OIF. "This demonstration will highlight the real progress area and give our members an opportunity to show the strides they have made in making together to build a better network."

"It's not only the chips that have to be faster and more efficient. Today, it is increasing development effort is also fast and efficient," adds Karen Liu, managing director with group. "The broad range of companies participating in the OIF PLL Interoperability I widespread recognition of that need. The activity of the OIF is a sign of increasing in the communications industry."



QUICK VOTE

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What's your opinion of the DC Circuit Court's ruling on the Triennial Review?

Love it.

Hate it.

Not sure.

Wake me when it reaches the Supreme Court.

The live SUPERDemo will feature the first demonstration of the OIF's CEI work in physical layer of electrical interfaces with signaling rates of 6+ and 11+ Gbits for chip-to-chip, chip-to-backplane electrical backplane applications. Participant companies will include ASSP, FPGA, ASIC, transmission channel, and test equipment vendors highlighting protocol testers; signal processing equipment, including eye diagrams and jitter measurements; video generation; and digital

The demonstration will also highlight the Serdes Framing Interface for a common electrical SONET framer and serial/deserializer parts for OC-192 interfaces (SFI-4.1 IA); the SFI-4.2 IA; Phase 2: System Interface for Physical and Link Layer Devices (SPI-4.2 IA); and the SPI-4.2 IA. These electrical interfaces define the transport protocol between ICs in equipment channels at aggregate rates.

The companies that will participate in the OIF's interoperability demonstration at SUPERCOMM 2003 include Agilent Technologies, AMCC, BitBlitz Communications, Gennum Corp., Ignis Optics, Iolon, Multiplex, NEC Electronics America, Santur, Tyco Electronics, Velio, Vitesse, and Xilinx.

View Results Only

Members of the OIF will be providing technical presentations based on the Forum's o area of the booth. For the schedule of presentations visit: < ahref=http://www.oiforum.com/public/supercomm_2003.html>www.oiforum.com/pt The OIF booth will also include a multimedia presentation on the OIF's UNI/NNI inte Interested in a subscription to Lightwave Magazine? that took place in early July 2003. [Click here](#) to subscribe!

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